

Product Information Sheet

EPO-TEK® EV2118-2

Date: February 2022 Recommended Cure: 150°C / 1 Hour

Rev:

No. of Components: Two

Mix Ratio by Weight: 1:1 Specific Gravity:

Part A: 2.53

Pot Life: 3 Days

Shelf Life- Bulk: One year at room temperature

Shelf Life- Syringe: One year at -40°C

150°C / 10 Minutes Part B: 3.33

120°C / 15 Minutes 100°C / 1 Hour

Minimum Alternative Cure(s):

May not achieve performance properties listed below

NOTES:

• Container(s) should be kept closed when not in use.

• Filled systems should be stirred thoroughly before mixing and prior to use.

• Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

<u>Product Description:</u> A silver-filled, electrically conductive epoxy designed for semiconductor and electronic assembly.

Typical Properties: Cure condition: varies as required Different batches, conditions & applications yield differing results. Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:		
* Color (before cure):	Part A: Shiny si	lver Part B: Shiny silver
* Consistency:	Smooth paste	
* Viscosity (23°C) @ 100 rpm:	1,500 - 3,000	cPs
Thixotropic Index:	4.4	
* Glass Transition Temp:	≥ 40	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -40-200°C @20°C/Min)
Shore A Hardness:	55	
Lap Shear @ 23°C:	428	psi
Die Shear @ 23°C:	≥ 5	Kg 1,778 psi
Degradation Temp:	325	°C
Weight Loss:		
@ 200°C:	0.61	%
@ 250°C:	0.84	%
@ 300°C:	1.58	%
Suggested Operating Temperature:	< 250	°C (Intermittent)
Storage Modulus:	130,977	psi
* Particle Size:	≤ 20	microns

ELECTRICAL AND THERMAL PROPERTIES:				
Thermal Conductivity:	4.0	W/mK		
* Volume Resistivity @ 23°C:	≤ 0.0005	Ohm-cm		